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(54) **TWISTABLE ELECTRONIC DEVICE
MODULE**

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(57) **ABSTRACT**

A twistable electronic device module including a twistable substrate, an electrode pattern layer, an insulating layer, a circuit layer, a plurality of circuit boards and a plurality of electronic devices is provided. The electrode pattern layer is disposed on the twistable substrate. The insulating layer is disposed on the electrode pattern layer. The edge of the insulating layer has an opening located at the edge of the twistable substrate and exposing a part of the electrode pattern layer. The circuit layer is disposed on the insulating layer and on the sidewall of the opening, and is connected with the electrode pattern layer. The plurality of circuit boards are disposed on the circuit layer, and each is electrically connected to the circuit layer. The plurality of electronic devices are disposed on the plurality of circuit boards, and each is electrically connected to a corresponding one of the plurality of circuit boards.

